



STGW20NC60VD

N-CHANNEL 30A - 600V TO-247

Very Fast PowerMESH™ IGBT

Table 1: General Features

| TYPE | V _{CES} | V _{CE(sat)} (Max) @25°C | I _C @100°C |
|--------------|------------------|-------------------------------------|--------------------------|
| STGW20NC60VD | 600 V | < 2.5 V | 30 A |

- OFF LOSSES INCLUDE TAIL CURRENT
- LOSSES INCLUDE DIODE RECOVERY ENERGY
- HIGH CURRENT CAPABILITY
- HIGH FREQUENCY OPERATION UP TO 50 KHz
- VERY SOFT ULTRA FAST RECOVERY ANTIPARALLEL DIODE
- LOWER C_{RES} /C_{IES} RATIO
- NEW GENERATION PRODUCTS WITH TIGHTER PARAMETER DISTRIBUTION

DESCRIPTION

Using the latest high voltage technology based on a patented strip layout, STMicroelectronics has designed an advanced family of IGBTs, the PowerMESH™ IGBTs, with outstanding performances. The suffix “V” identifies a family optimized for high frequency applications.

APPLICATIONS

- HIGH FREQUENCY INVERTERS
- SMPS and PFC IN BOTH HARD SWITCH AND RESONANT TOPOLOGIES
- UPS
- MOTOR DRIVERS

Table 2: Order Codes

| SALES TYPE | MARKING | PACKAGE | PACKAGING |
|--------------|------------|---------|-----------|
| STGW20NC60VD | GW20NC60VD | TO-247 | TUBE |

Figure 1: Package

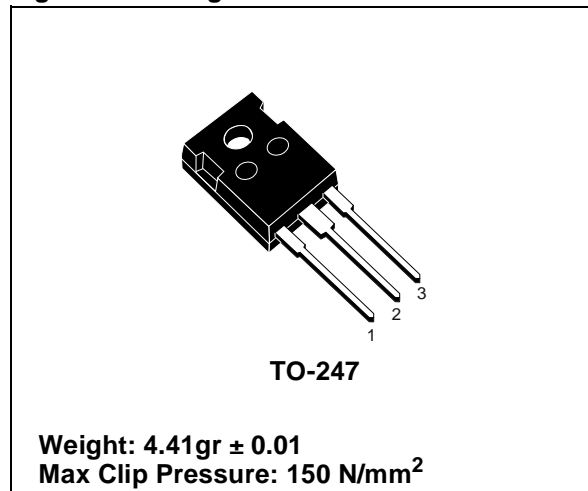


Figure 2: Internal Schematic Diagram

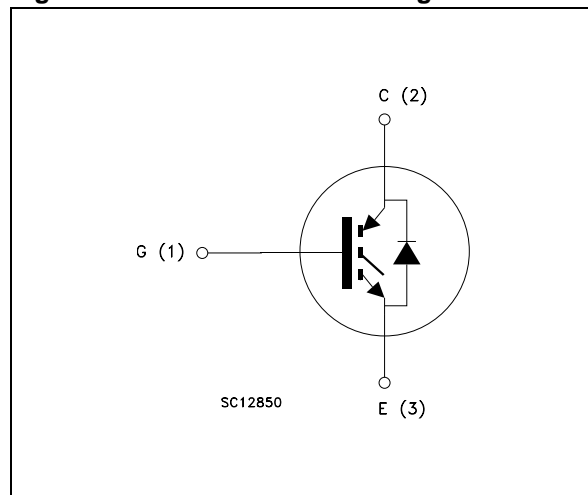


Table 3: Absolute Maximum ratings

| Symbol | Parameter | Value | Symbol |
|---------------------|--|-------------|--------|
| V _{CES} | Collector-Emitter Voltage (V _{GS} = 0) | 600 | V |
| V _{ECR} | Reverse Battery Protection | 20 | V |
| V _{GE} | Gate-Emitter Voltage | ± 20 | V |
| I _C | Collector Current (continuous) at 25°C (#) | 60 | A |
| I _C | Collector Current (continuous) at 100°C (#) | 30 | A |
| I _{CM} (1) | Collector Current (pulsed) | 100 | A |
| I _f | Diode RMS Forward Current at T _C = 25°C | 30 | A |
| P _{TOT} | Total Dissipation at T _C = 25°C | 200 | W |
| | Derating Factor | 1.6 | W/°C |
| T _{stg} | Storage Temperature | - 55 to 150 | °C |
| T _j | Operating Junction Temperature | | |

(1)Pulse width limited by max. junction temperature.

Table 4: Thermal Data

| | | Min. | Typ. | Max. | |
|-----------------------|--|------|------|-------|------|
| R _{thj-case} | Thermal Resistance Junction-case (IGBT) | -- | -- | 0.625 | °C/W |
| R _{thj-case} | Thermal Resistance Junction-case (Diode) | -- | -- | 1.5 | °C/W |
| R _{thj-amb} | Thermal Resistance Junction-ambient | -- | -- | 50 | °C/W |
| T _L | Maximum Lead Temperature for Soldering Purpose (1.6 mm from case, for 10 sec.) | | 300 | | °C |

ELECTRICAL CHARACTERISTICS (T_{CASE} =25°C UNLESS OTHERWISE SPECIFIED)

Table 5: Off

| Symbol | Parameter | Test Conditions | Min. | Typ. | Max. | Unit |
|----------------------|---|---|------|------|---------|----------|
| V _{BR(CES)} | Collectro-Emitter Breakdown Voltage | I _C = 1 mA, V _{GE} = 0 | 600 | | | V |
| I _{CES} | Collector-Emitter Leakage Current (V _{CE} = 0) | V _{GE} = Max Rating T _C =25°C T _C =125°C | | | 10 1 | µA mA |
| I _{GES} | Gate-Emitter Leakage Current (V _{CE} = 0) | V _{GE} = ± 20 V , V _{CE} = 0 | | | ± 100 | nA |

Table 6: On

| Symbol | Parameter | Test Conditions | Min. | Typ. | Max. | Unit |
|----------------------|--------------------------------------|--|------|------------|------|--------|
| V _{GE(th)} | Gate Threshold Voltage | V _{CE} = V _{GE} , I _C = 250 µA | 3.75 | | 5.75 | V |
| V _{CE(SAT)} | Collector-Emitter Saturation Voltage | V _{GE} = 15 V, I _C = 20A, T _j = 25°C V _{GE} = 15 V, I _C = 20A, T _j = 125°C | | 1.8 1.7 | 2.5 | V V |

(#) Calculated according to the iterative formula:

$$I_C(T_C) = \frac{T_{JMAX} - T_C}{R_{THJ-C} \times V_{CESAT(MAX)}(T_C, I_C)}$$

ELECTRICAL CHARACTERISTICS (CONTINUED)

Table 7: Dynamic

| Symbol | Parameter | Test Conditions | Min. | Typ. | Max. | Unit |
|-------------------------------------|---|--|------|-------------------|------|----------------|
| $g_{fs}(1)$ | Forward Transconductance | $V_{CE} = 15 \text{ V}$, $I_C = 20 \text{ A}$ | | 15 | | S |
| C_{ies} C_{oes} C_{res} | Input Capacitance Output Capacitance Reverse Transfer Capacitance | $V_{CE} = 25 \text{ V}$, $f = 1 \text{ MHz}$, $V_{GE} = 0$ | | 2200 225 50 | | pF pF pF |
| Q_g Q_{ge} Q_{gc} | Total Gate Charge Gate-Emitter Charge Gate-Collector Charge | $V_{CE} = 390 \text{ V}$, $I_C = 20 \text{ A}$, $V_{GE} = 15 \text{ V}$, (see Figure 21) | | 100 16 45 | 140 | nC nC nC |
| I_{CL} | Turn-Off SOA Minimum Current | $V_{clamp} = 480 \text{ V}$, $T_j = 150^\circ\text{C}$ $R_G = 10 \Omega$, $V_{GE} = 15 \text{ V}$ | 100 | | | A |

Table 8: Switching On

| Symbol | Parameter | Test Conditions | Min. | Typ. | Max. | Unit |
|---|--|--|------|---------------------------|------|---|
| $t_{d(on)}$ t_r $(di/dt)_{on}$ $E_{on}(2)$ | Turn-on Delay Time Current Rise Time Turn-on Current Slope Turn-on Switching Losses | $V_{CC} = 390 \text{ V}$, $I_C = 20 \text{ A}$ $R_G = 3.3 \Omega$, $V_{GE} = 15 \text{ V}$, $T_j = 25^\circ\text{C}$ (see Figure 19) | | 31 11 1600 220 | 300 | ns ns A/ μs μJ |
| $t_{d(on)}$ t_r $(di/dt)_{on}$ $E_{on}(2)$ | Turn-on Delay Time Current Rise Time Turn-on Current Slope Turn-on Switching Losses | $V_{CC} = 390 \text{ V}$, $I_C = 20 \text{ A}$ $R_G = 3.3 \Omega$, $V_{GE} = 15 \text{ V}$, $T_j = 125^\circ\text{C}$ (see Figure 19) | | 31 11.5 1500 450 | | ns ns A/ μs μJ |

2) E_{on} is the turn-on losses when a typical diode is used in the test circuit in figure 2. If the IGBT is offered in a package with a co-pack diode, the co-pack diode is used as external diode. IGBTs & DIODE are at the same temperature (25°C and 125°C)

Table 9: Switching Off

| Symbol | Parameter | Test Conditions | Min. | Typ. | Max. | Unit |
|---|--|--|------|---------------------------------|------------|--|
| $t_r(V_{off})$ $t_{d(off)}$ t_f $E_{off}(3)$ E_{ts} | Off Voltage Rise Time Turn-off Delay Time Current Fall Time Turn-off Switching Loss Total Switching Loss | $V_{CC} = 390 \text{ V}$, $I_C = 20 \text{ A}$, $R_{GE} = 3.3 \Omega$, $V_{GE} = 15 \text{ V}$ $T_j = 25^\circ\text{C}$ (see Figure 19) | | 28 100 75 330 550 | 450 750 | ns ns ns μJ μJ |
| $t_r(V_{off})$ $t_{d(off)}$ t_f $E_{off}(3)$ E_{ts} | Off Voltage Rise Time Turn-off Delay Time Current Fall Time Turn-off Switching Loss Total Switching Loss | $V_{CC} = 390 \text{ V}$, $I_C = 20 \text{ A}$, $R_{GE} = 3.3 \Omega$, $V_{GE} = 15 \text{ V}$ $T_j = 125^\circ\text{C}$ (see Figure 19) | | 66 150 130 770 1220 | | ns ns ns μJ μJ |

(3) Turn-off losses include also the tail of the collector current.

Table 10: Collector-Emitter Diode

| Symbol | Parameter | Test Conditions | Min. | Typ. | Max. | Unit |
|---|--|---|------|--------------------------------|------|--------------------------|
| V_f | Forward On-Voltage | $I_f = 10\text{ A}$ $I_f = 10\text{ A}, T_j = 125\text{ °C}$ | | 1.3 1 | 2.0 | V V |
| t_{rr} t_a Q_{rr} I_{rrm} S | Reverse Recovery Time Reverse Recovery Charge Reverse Recovery Current Softness factor of the diode | $I_f = 20\text{ A}, V_R = 40\text{ V},$ $T_j = 25\text{ °C}, di/dt = 100\text{ A}/\mu\text{s}$ (see Figure 22) | | 44 32 66 3 0.375 | | ns ns nC A A |
| t_{rr} t_a Q_{rr} I_{rrm} S | Reverse Recovery Time Reverse Recovery Charge Reverse Recovery Current Softness factor of the diode | $I_f = 20\text{ A}, V_R = 40\text{ V},$ $T_j = 125\text{ °C}, di/dt = 100\text{ A}/\mu\text{s}$ (see Figure 22) | | 88 56 237 5.4 0.57 | | ns ns nC A A |

Figure 3: Output Characteristics

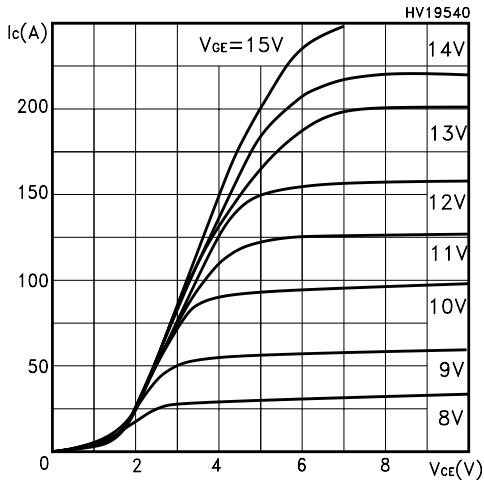


Figure 4: Transconductance

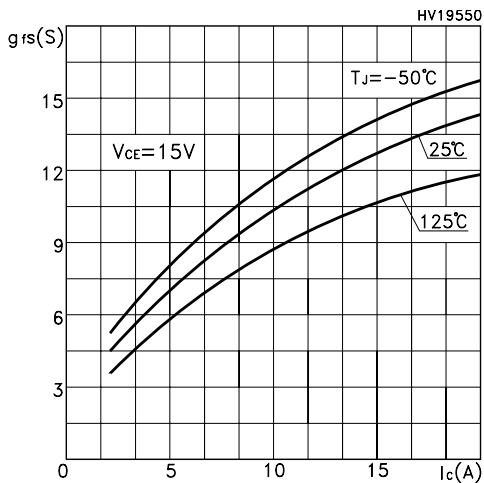


Figure 5: Collector-Emitter On Voltage vs Collector Current

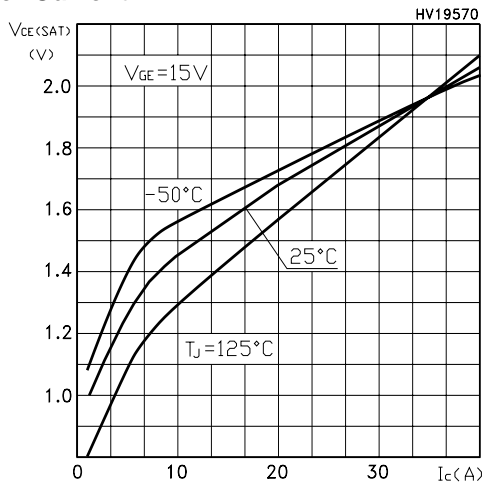


Figure 6: Transfer Characteristics

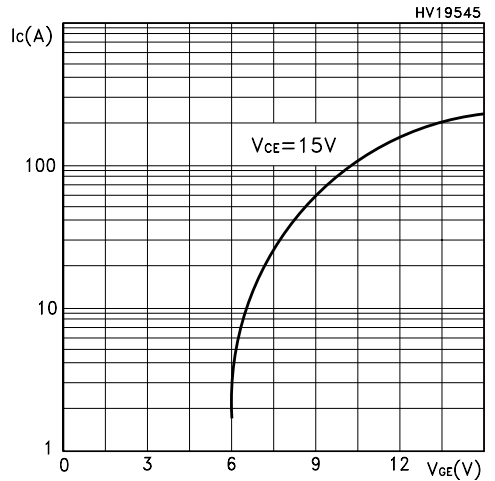


Figure 7: Collector-Emitter On Voltage vs Temperature

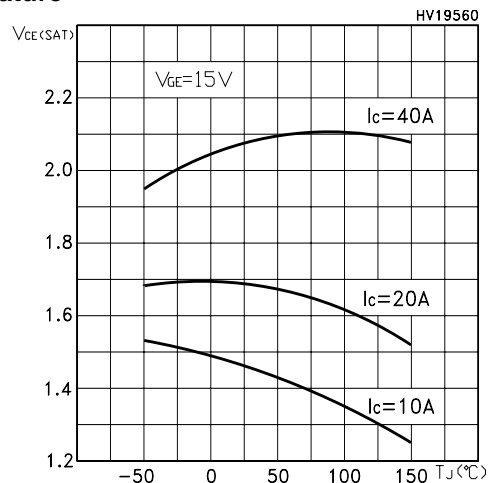


Figure 8: Normalized Gate Threshold vs Temperature

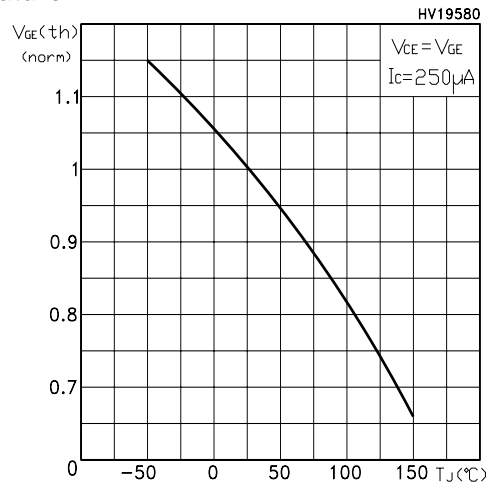


Figure 9: Normalized Breakdown Voltage vs Temperature

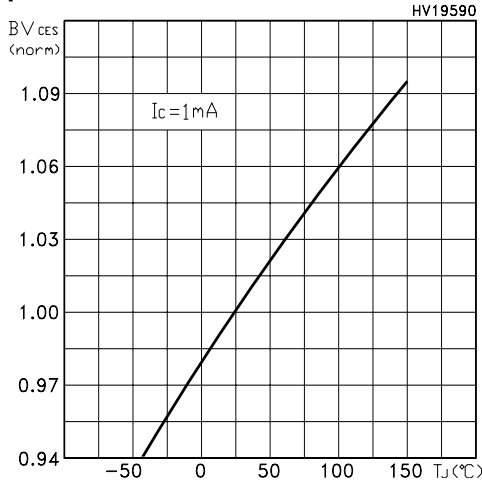


Figure 10: Capacitance Variations

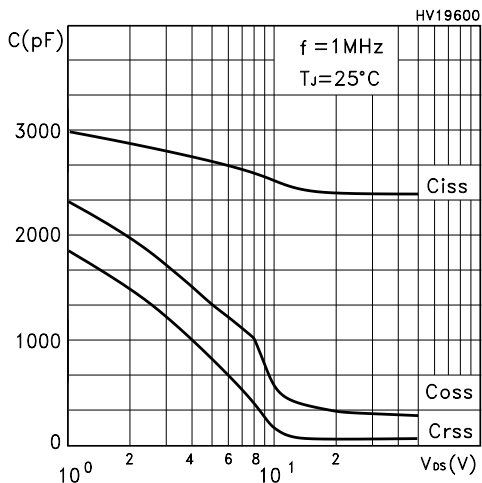


Figure 11: Total Switching Losses vs Gate Resistance

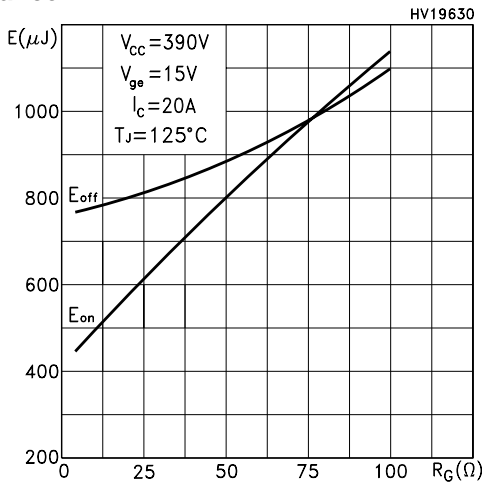


Figure 12: Gate Charge vs Gate-Emitter Voltage

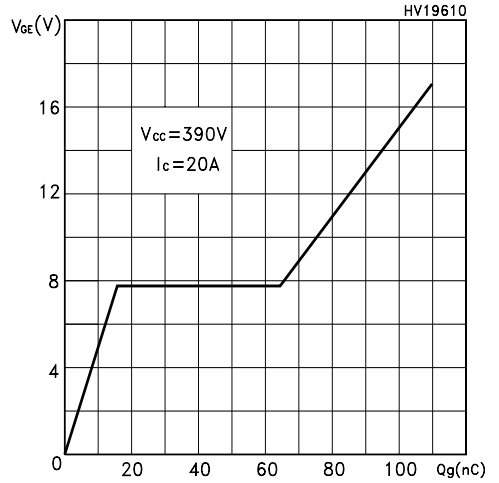


Figure 13: Total Switching Losses vs Temperature

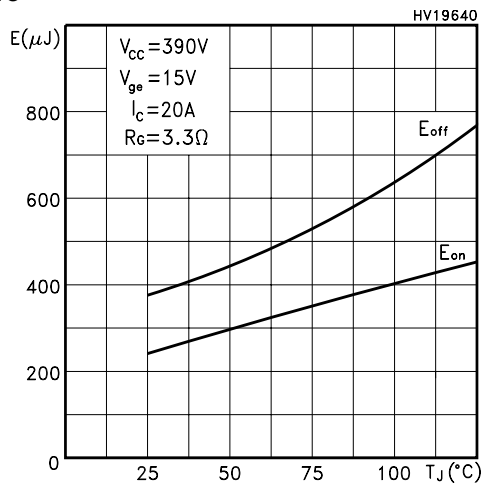


Figure 14: Total Switching Losses vs Collector Current

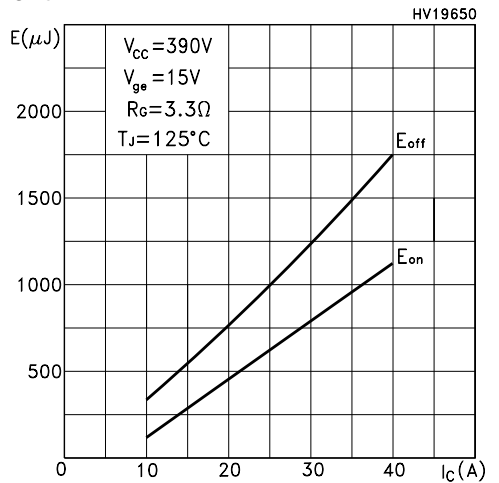


Figure 15: Thermal Impedance

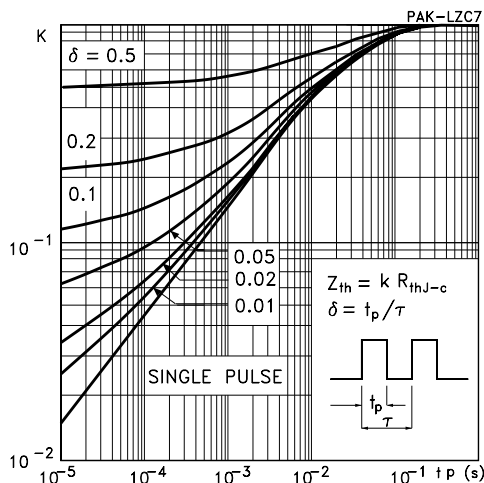


Figure 16: Turn-Off SOA

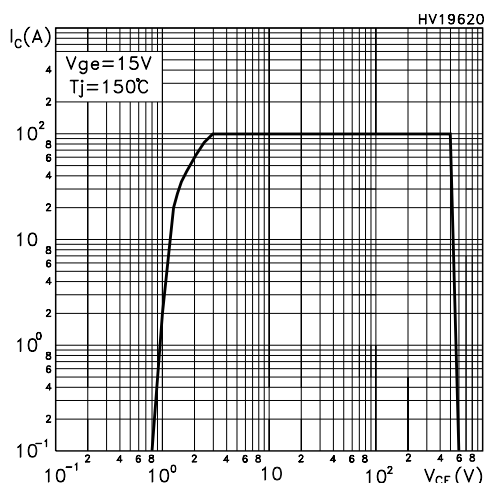


Figure 17: Emitter-Collector Diode Characteristics

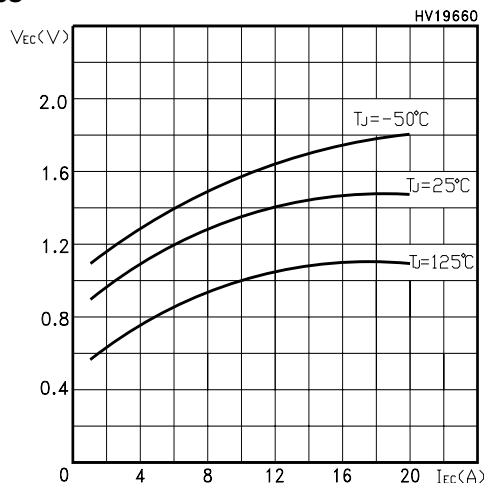
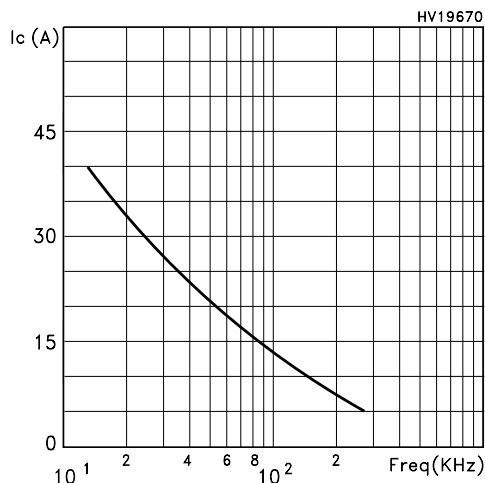


Figure 18: Ic vs Frequency



For a fast IGBT suitable for high frequency applications, the typical collector current vs. maximum operating frequency curve is reported. That frequency is defined as follows:

$$f_{MAX} = (P_D - P_C) / (E_{ON} + E_{OFF})$$

1) The maximum power dissipation is limited by maximum junction to case thermal resistance:

$$P_D = \Delta T / R_{THJ-C}$$

considering $\Delta T = T_J - T_C = 125^{\circ}C - 75^{\circ}C = 50^{\circ}C$

2) The conduction losses are:

$$P_C = I_C * V_{CE(SAT)} * \delta$$

with 50% of duty cycle, V_{CESAT} typical value @ 125°C.

3) Power dissipation during ON & OFF commutations is due to the switching frequency:

$$P_{SW} = (E_{ON} + E_{OFF}) * freq.$$

4) Typical values @ 125°C for switching losses are used (test conditions: $V_{CE} = 390V$, $V_{GE} = 15V$, $R_G = 3.3 \text{ Ohm}$). Furthermore, diode recovery energy is included in the E_{ON} (see note 2), while the tail of the collector current is included in the E_{OFF} measurements (see note 3).

Figure 19: Test Circuit for Inductive Load Switching

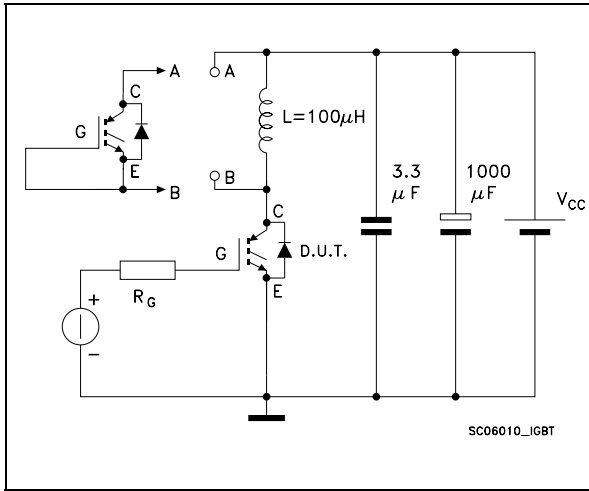


Figure 20: Switching Waveforms

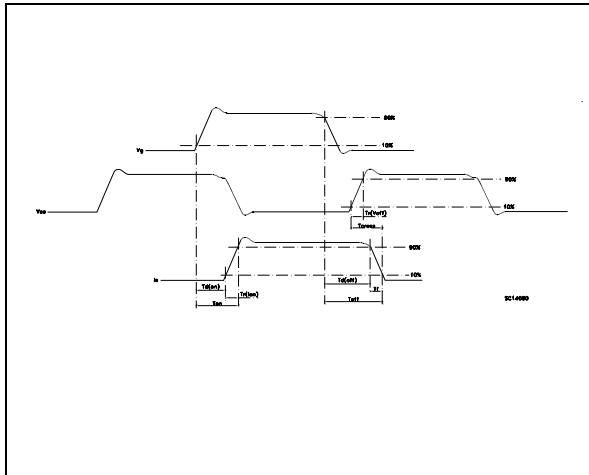


Figure 21: Gate Charge Test Circuit

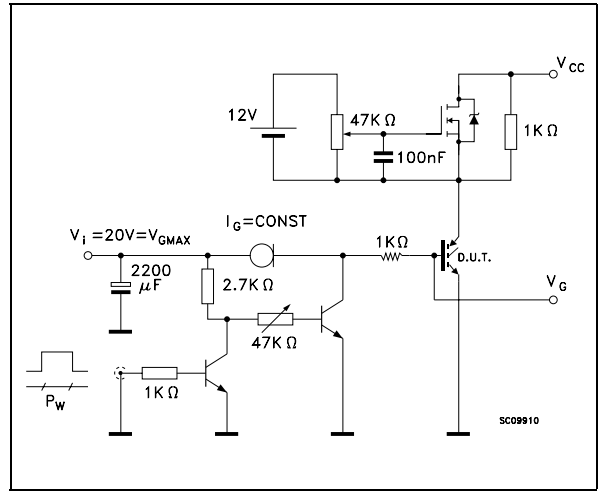


Figure 22: Diode Recovery Times Waveform

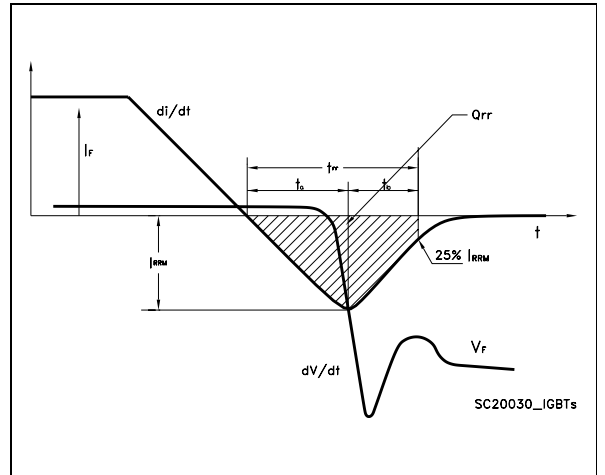
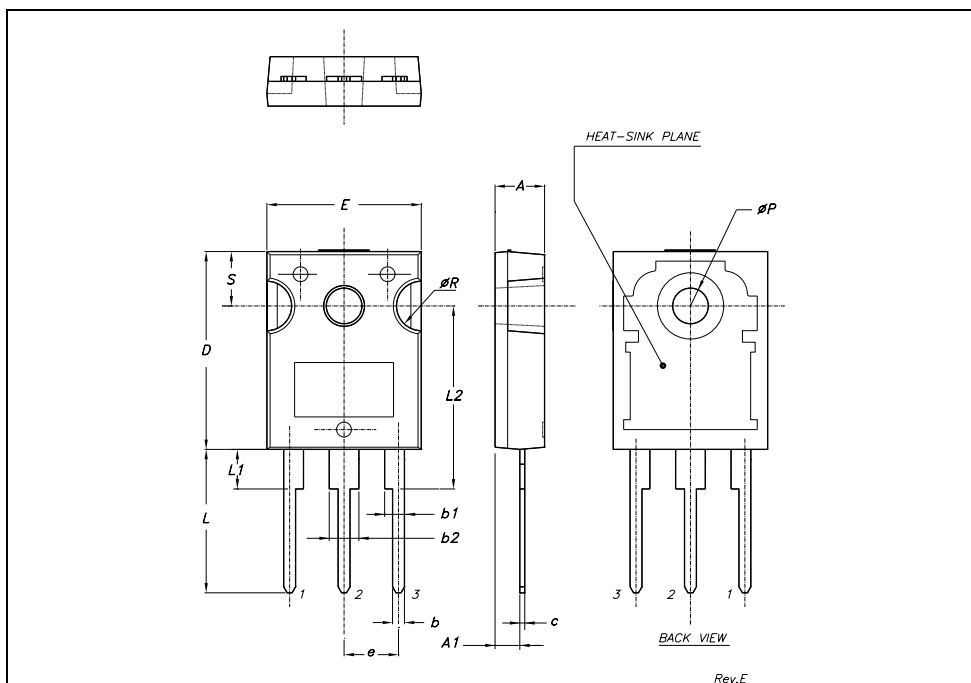


Table 11: Revision History

| Date | Revision | Description of Changes |
|--------------|----------|---|
| 12-July-2004 | 4 | Stylesheet update. Added Max Values see Table 8 and 9 Added Figure 22 |

TO-247 MECHANICAL DATA

| DIM. | mm. | | | inch | | |
|------|-------|-------|-------|-------|-------|-------|
| | MIN. | TYP. | MAX. | MIN. | TYP. | MAX. |
| A | 4.85 | | 5.15 | 0.19 | | 0.20 |
| A1 | 2.20 | | 2.60 | 0.086 | | 0.102 |
| b | 1.0 | | 1.40 | 0.039 | | 0.055 |
| b1 | 2.0 | | 2.40 | 0.079 | | 0.094 |
| b2 | 3.0 | | 3.40 | 0.118 | | 0.134 |
| c | 0.40 | | 0.80 | 0.015 | | 0.03 |
| D | 19.85 | | 20.15 | 0.781 | | 0.793 |
| E | 15.45 | | 15.75 | 0.608 | | 0.620 |
| e | | 5.45 | | | 0.214 | |
| L | 14.20 | | 14.80 | 0.560 | | 0.582 |
| L1 | 3.70 | | 4.30 | 0.14 | | 0.17 |
| L2 | | 18.50 | | | 0.728 | |
| øP | 3.55 | | 3.65 | 0.140 | | 0.143 |
| øR | 4.50 | | 5.50 | 0.177 | | 0.216 |
| S | | 5.50 | | | 0.216 | |



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